FEATURES

- DOUBLE LAYER CONSTRUCTION
- POWER BACK-UP FOR CMOS DEVICES
- SURFACE MOUNTABLE V-CHIP STYLE
- LEAD-FREE FINISH

RoHS Compliant High Temperature Reflow +260°C



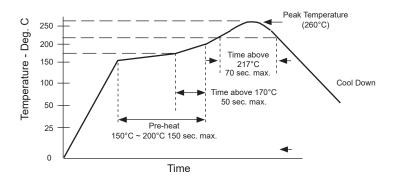
CHARACTERISTICS

Rated Voltage Range	3.5 & 5.5VDC		II	
Rated Capacitance Range	0.047F ~ 0.47F (47,000μF ~ 470,000μF)	Super Capacitor		
Operating Temp. Range	-40°C ~ +85°C	Application Guide		
Capacitance Tolerance	+80%/-20% (Z)			
1 11:5 -	Δ Capacitance Change	Within ±30% of initial measured value		
Load Life Test +85°C 240 hours	Maximum ESR	Maximum ESR Less than 200% of the specified maximum		
200 0 240 110413	Current at 30 minutes	Less than 200% of the specified maximum value		
T	Δ Capacitance Change	Within +80%/-20% of specified value		
Temperature Cycling (5 cycles, -25 ~ +70°C	Maximum ESR	Less than specified maximum value		
(0 0)0100, 20 170 0	Current at 30 minutes	Less than specified maximum value		
	Δ Capacitance Change	Within ±20% of initial measured value		
Humidity Resistance	Maximum ESR	Less than 120% of the specified maximum value		
(240 hours @ 40°C/90% RH)	Current at 30 minutes	Less than 120% of the sp	pecified maximum value	

STANDARD VALUES AND SPECIFICATIONS

NIC P/N	Capacitance Value (F) Discharge	Working Voltage (VDC)	Max. Current @ 30 minutes (mA)	Max. ESR @ 1KHz (Ω)
NEXCW104Z3.5V10.7X5.5TRF	0.10	3.5	0.090	100
NEXCW224Z3.5V10.7X5.5TRF	0.22	3.5	0.200	50
NEXCW474Z3.5V10.7X8.5TRF	0.47	3.5	0.420	50
NEXCW473Z5.5V10.7X5.5TRF	0.047	5.5	0.071	100
NEXCW104Z5.5V10.7X5.5TRF	0.10	5.5	0.150	50
NEXCW224Z5.5V10.7X8.5TRF	0.22	5.5	0.330	50

HIGH TEMPERATURE REFLOW PROFILE



Peak Temperature	+260°C
Time above +255°C	10 sec. max.
Time above +230°C	45 sec. max.
Time above +220°C	60 sec. max.
Time above +217°C	70 sec. max.
150°C ~ +200°C (with time above +170°C 50 sec. max.)	150 sec. max.

- 1. The temperatures shown are the surface temperature values on the top of the can and on the capacitor terminals.
- 2. 2x reflow process maximum. Capacitor should be allowed to return to room temperature before second reflow process.

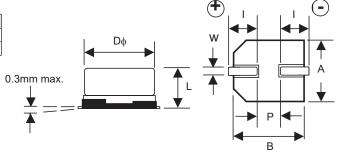
PRECAUTIONS

Please review the notes on correct use, safety and precautions found at https://www.niccomp.com/resource/files/double/Double_Layer_Capacitor_Guide_0810-RevBrA7.pdf If in doubt or uncertainty, please review your specific application - process details with NIC's technical support personnel: tpmg@niccomp.com



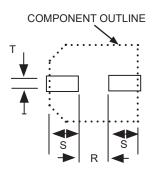
CASE DIMENSIONS (mm)

Case Size	Dφ ±	L max.	A/B ±0.2	I	W	Р
10.7 x 5.5	10.7	5.5	10.8	3.9 ±0.5	1.2 ± 0.1	5.0
10.7 x 8.5	10.7	8.5	10.8	3.9 ±0.5	1.2 ± 0.1	5.0



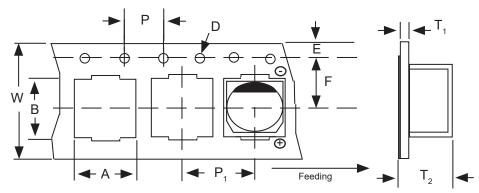
LAND PATTERN DIMENSIONS (mm)

Case Diameter	R	S	Т
10.7	5.0	4.9	2.5



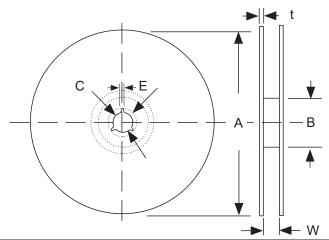
CARRIER TAPE DIMENSIONS (mm)

Case Size	Α	В	D	Е	F	Р	P₁	T,	T ₂	W	Quantity/Reel
10.7 x 5.5	11.4	13.0	1.55	1.75	11.5	4.0	16.0	0.4	6.0	24.0	1,000
10.7 x 8.5	11.4	13.0	1.55	1.75	11.5	4.0	16.0	0.4	8.4	24.0	500

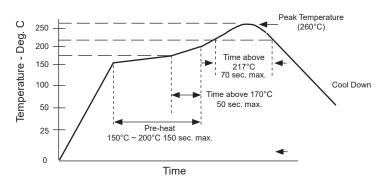


REEL DIMENSIONS (mm)

Case Size	A ± 2.0	B ± 1.0	C ± 0.5	D ± 0.8	E ± 0.5	W	t
10.7 x 5.5	380	80.0	13.0	21.0	2.0	25.5 ± 0.5	2.0
10.7 x 8.5	380	100.0	13.0	21.0	2.0	25.5 ± 1.0	2.0



HIGH TEMPERATURE REFLOW PROFILE

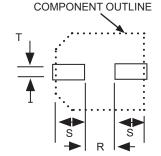


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Time above +220°C	60 sec. max.
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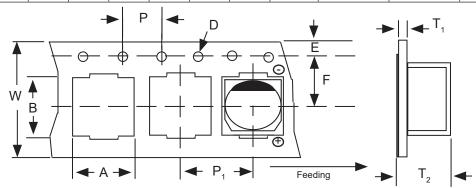
LAND PATTERN DIMENSIONS (mm)

Case Diameter	R	S	Т	
10.7	5.0	4.9	2.5	

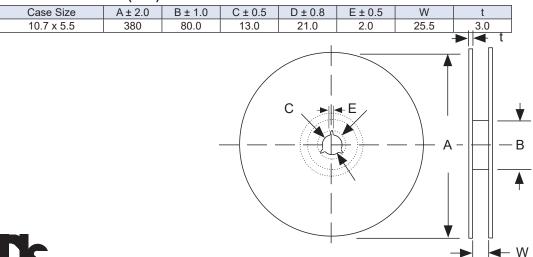


CARRIER TAPE DIMENSIONS (mm)

Case Size	Α	В	D	Е	F	G	Р	P,	T,	T,	W	Quantity/Reel
10.7 x 5.5	11.4	13.0	1.55	1.75	11.5	-	4.0	16.0	0.4	6.0	24.0	1,000



REEL DIMENSIONS (mm)



V-Chip Memory Back-Up Capacitors

RELIABILITY TEST

Item		Specif	ication	Test Method JIS C 5260-1	
	0, 0	Capacitance	>50% of initial measured value		
	Step 2	ESR	<400% of initial measured value	Section 4.17	
	04 0	Capacitance	>30% of initial measured value	Phase 1: +25°C ± 2°C	
	Step 3	ESR	<700% of initial measured value	Phase 2: -25°C ± 2°C	
Tamananatuwa Ohawatawiatiaa		Capacitance	>200% of initial measured value		
Temperature Characteristics	Step 5	ESR	Meets initial specification	Phase 3: -40°C ± 2°C	
		Current @ 30 minutes	1.5CV (mA) or less	Phase 4: +25°C ± 2°C	
		Capacitance	±20% of initial measured value*	Phase 5: +85°C ± 2°C	
	Step 6	ESR	Meets initial specification*	Phase 6: +25°C ± 2°C	
		Current after 30 minutes	Meets initial specification*		
		Capacitance		Section 4.13	
Vibration		ESR	Meets initial specifications	Frequency: 10 ~ 55Hz	
Vibration	Cu	rrent after 30 minutes			
	Appearance		No obvious abnormalities	Duration: 6 hours	
		Capacitance			
Resistance to Soldering Heat		ESR	Meets initial specifications*	See NEXCW datasheet for reflow	
resistance to coldening fleat	Cu	rrent after 30 minutes		soldering conditions	
	Appearance		No obvious abnormalities		
		Capacitance		Section 4.12	
Temperature Cycling		ESR	Meets initial specifications*	Temp.: -40°C > +25°C > +85°C	
remperature Cycling	Cu	rrent after 30 minutes		Number of cycles: 5	
		Appearance	No obvious abnormalities		
		Capacitance	±20% of initial measured value*	Section 4.14	
Decistance to		ESR	<120% of initial specified value*	Temperature: +40°C ± 2°C	
Resistance to High Temperature & Humidity	Cu	rrent after 30 minutes	<120% of initial specified value*	Relative Humidity: 90% ~ 95%	
		Appearance	No obvious abnormalities	Duration: 240 hours ± 8 hours	
		Capacitance	±30% of initial measured value*	Section 4.15	
		ESR	<200% of initial specified value*	Temperature: +85°C ± 2°C	
High Temperature Load Life	Cu	rrent after 30 minutes	<200% of initial specified value*	Voltage: 5.5Vdc	
High Temperature Load Life				Series resistance: 0Ω	
	Appearance		No obvious abnormalities	Duration: 240 hours +8/-0 hours	

^{*} Stablize component at +25°C prior to making measurements of characteristics.